

Attorney Docket No.: 0140153  
Application Serial No.: 10/649,577

**List of Claims:**

**Claim 1 (Currently Amended):** A method for forming a package for an electrical device, said method comprising the steps of:

attaching a removable material to a surface of a conductive material ~~before one or more isolated conductive features have been formed within said conductive material;~~

forming ~~said~~ isolated conductive features within said conductive material;

attaching encapsulant to said isolated conductive features and said removable material;  
~~wherein said attaching step is performed before a singulation process is performed to separate said package; and~~

removing said removable material from said conductive features and said encapsulant;  
~~wherein the removing said material step is performed after the singulation process is performed to separate said package.~~

**Claim 2 (Original):** The method for forming a package for the electronic device of claim 1, wherein said forming step includes patterning a surface of said conductive material with a material resistant to an etchant and etching said conductive material with said etchant.

**Claim 3 (Original):** The method for forming a package for the electronic device of claim 1, further comprising the step of forming a die attach pad within said conductive material.

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**Claim 4 (Previously Presented):** The method for forming a package for the electronic device of claim 1, further comprising the step of coupling the device to said die attach pad.

**Claim 5 (Original):** The method for forming a package for an electronic device of claim 1, further comprising the step of electrically coupling an input/output portion of the device to said isolated conductive feature.

**Claim 6 (Original):** The method for forming a package for the electronic device of claim 1, further comprising the step of singulating individual packaged devices.

**Claim 7 (Original):** The method of claim 1, wherein the removable material is water soluble adhesive.

**Claim 8 (Original):** The method of claim 7, wherein the removable material is removed with deionized water.

**Claims 9-15 (Cancelled)**

**Claim 16 (Previously Presented):** The method of claim 1, wherein the removable material is mold stencil that is used in said attaching encapsulant step.

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**Claim 17 (Previously Presented):** The method of claim 1, wherein the removable material comprises a polyimide material and a water soluble adhesive.

**Claims 18-19 (Cancelled)**

**Claim 20 (Previously Presented):** The method of claim 1, wherein said conductive material comprises a metal frame.

**Claim 21 (Previously Presented):** The method of claim 20, wherein the metal frame comprises a leadframe.

**Claim 22 (Previously Presented):** The method of claim 21, further comprising the step of forming a die attach pad within said conductive materials, wherein said die attach pad is not offset from said isolated conductive features.

**Claim 23 (Previously Presented):** The method of claim 21, wherein a single row of connectors is formed around a perimeter of said leadframe.

**Claim 24 (Previously Presented):** The method of claim 20, wherein said metal frame comprises a metal sheet.

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**Claim 25 (Previously Presented):** The method of claim 24, wherein multiple rows of connectors are formed around a perimeter of the metal sheet.

**Claim 26 (Previously Presented):** The method of claim 20, wherein the removable material covers substantially the entire bottom surface of said metal frame.

**Claim 27 (Previously Presented):** The method of claim 4, wherein the electronic device is coupled to said die attach pad via conductive epoxy.

**Claim 28 (New):** A method for forming a package for an electrical device, said method comprising the steps of:

attaching a removable material to a surface of a conductive material before one or more isolated conductive features have been formed within said conductive material;

forming said isolated conductive features within said conductive material;

attaching encapsulant to said isolated conductive features and said removable material, wherein said attaching step is performed before a singulation process is performed to separate said package; and

removing said removable material from said conductive features and said encapsulant, wherein the removing said material step is performed after the singulation process is performed to separate said package.